

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
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Property Type	Number
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ASSIGNMENT

For good and valuable consideration, the sufficiency and receipt of which is hereby acknowledged, as a below named inventor, I hereby sell and assign to SHIN-ETSU CHEMICAL CO., LTD.

of 6-1, Otemachi 2-chome, Chiyoda-ku, Tokyo 1000004, JAPAN

its successors and assigns or other legal representatives all my rights, title and interest, in and for the United States of America, in and to

METHOD FOR MANUFACTURING COMPOSITE WAFERS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefore, filed September 14, 2012 as International Application No. PCT/JP2012/073629 and all United States Letters Patent which may be granted therefore, and all divisions, continuations, reissues, reexaminations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said SHIN-ETSU CHEMICAL CO., LTD., its successors, assigns or other legal representatives, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said SHIN-ETSU CHEMICAL CO., LTD.

(Full Name)

(Signature)

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